

## WPMD2075

**Dual P-Channel, -20V, -3.6A, Power MOSFET**

[Http://www.sh-willsemi.com](http://www.sh-willsemi.com)

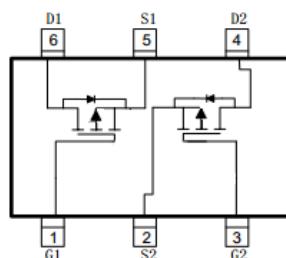
<b>V<sub>DS</sub> (V)</b>	<b>Typical R<sub>ds(on)</sub> (mΩ)</b>
<b>-20</b>	60@ V <sub>GS</sub> =-10V
	70@ V <sub>GS</sub> =-4.5V
	100@ V <sub>GS</sub> =-2.5V



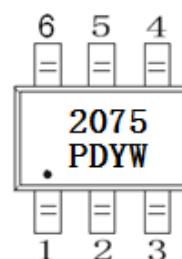
## Descriptions

The WPMD2075 is the Dual P-Channel logic mode power field effect transistors are produced using high cell density, DMOS trench technology. This high density process is especially tailored to minimize on-state resistance. These devices are particularly suited for low voltage application, notebook computer power management and other battery powered circuits where high-side switching.

**SOT-23-6L**



**Pin configuration (Top view)**



## Features

- Trench Technology
- Supper high density cell design
- Excellent ON resistance for higher DC current
- Extremely Low Threshold Voltage
- SOT-23-6L package design

2075 = Device Code  
PD = Special Code  
Y = Year  
W = Week

## Applications

### Marking

- Power Management
- DC-DC converter circuit
- Simple drive requirement
- Load Switch
- Charging

### Order information

Device	Package	Shipping
WPMD2075-6/TR	SOT-23-6L	3000/Reel&Tape

## Absolute Maximum ratings

Parameter	Symbol	10 S	Steady State	Unit
Drain-Source Voltage	V <sub>DS</sub>	-20	±12	V
Gate-Source Voltage	V <sub>GS</sub>	±12		
Continuous Drain Current <sup>a d</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	-3.6	A
	T <sub>A</sub> =70°C		-2.9	
Maximum Power Dissipation <sup>a d</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	1.2	W
	T <sub>A</sub> =70°C		0.7	
Continuous Drain Current <sup>b d</sup>	T <sub>A</sub> =25°C	I <sub>D</sub>	-3.3	A
	T <sub>A</sub> =70°C		-2.6	
Maximum Power Dissipation <sup>b d</sup>	T <sub>A</sub> =25°C	P <sub>D</sub>	1.0	W
	T <sub>A</sub> =70°C		0.6	
Pulsed Drain Current <sup>c</sup>	I <sub>DM</sub>	-20		A
Operating Junction Temperature	T <sub>J</sub>	150		°C
Storage Temperature Range	T <sub>stg</sub>	-55 to 150		°C

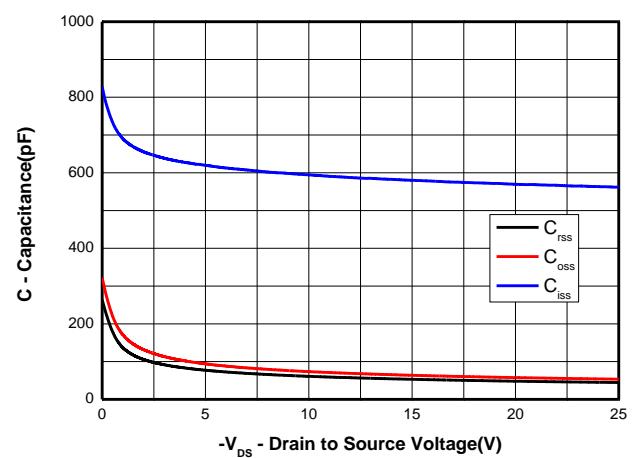
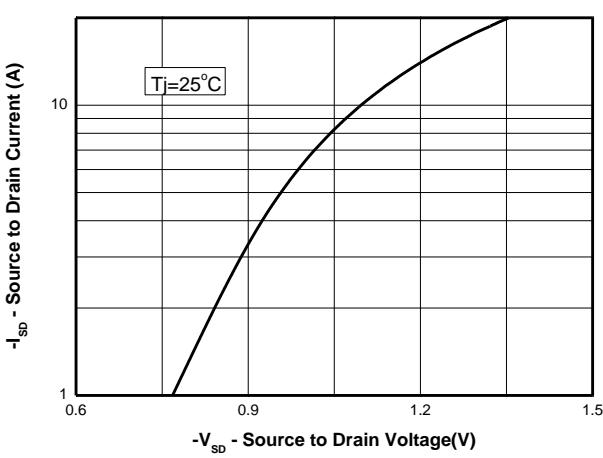
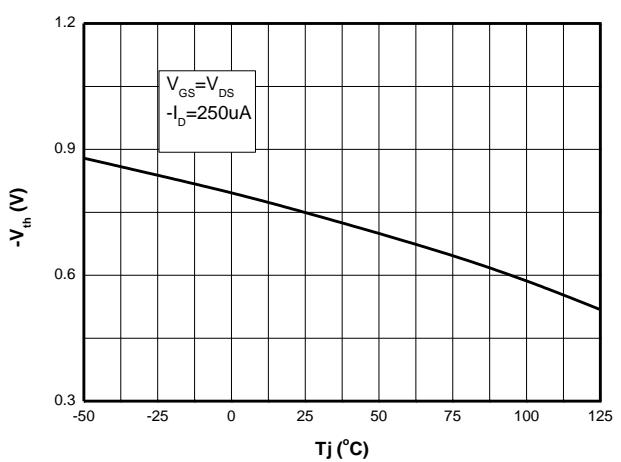
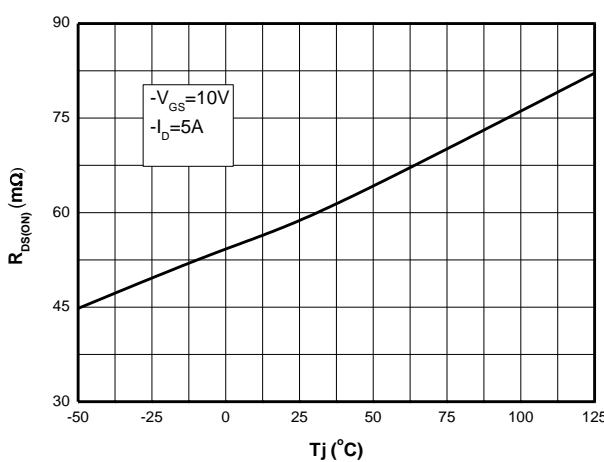
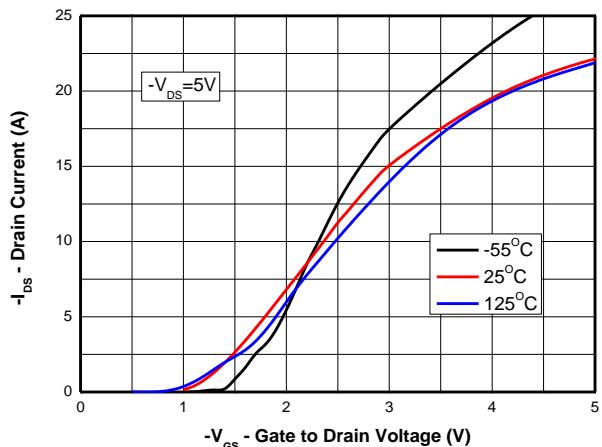
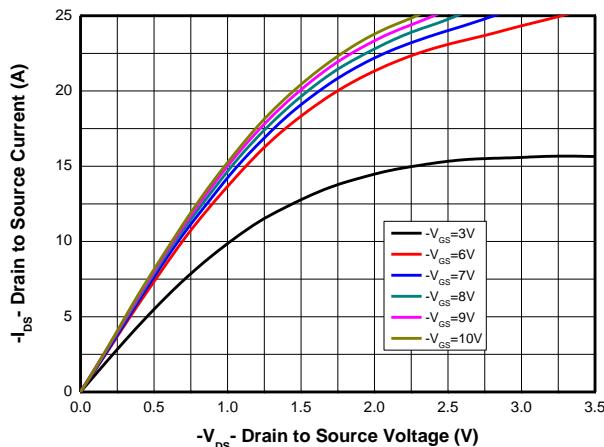
## Thermal resistance ratings

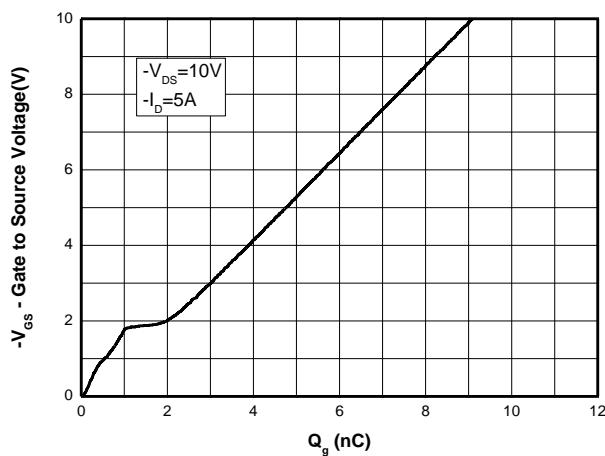
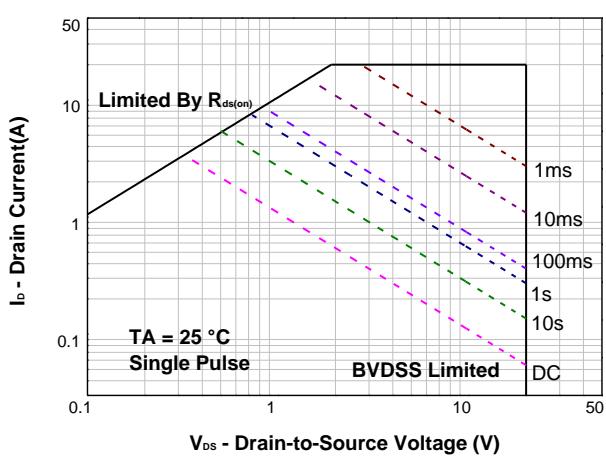
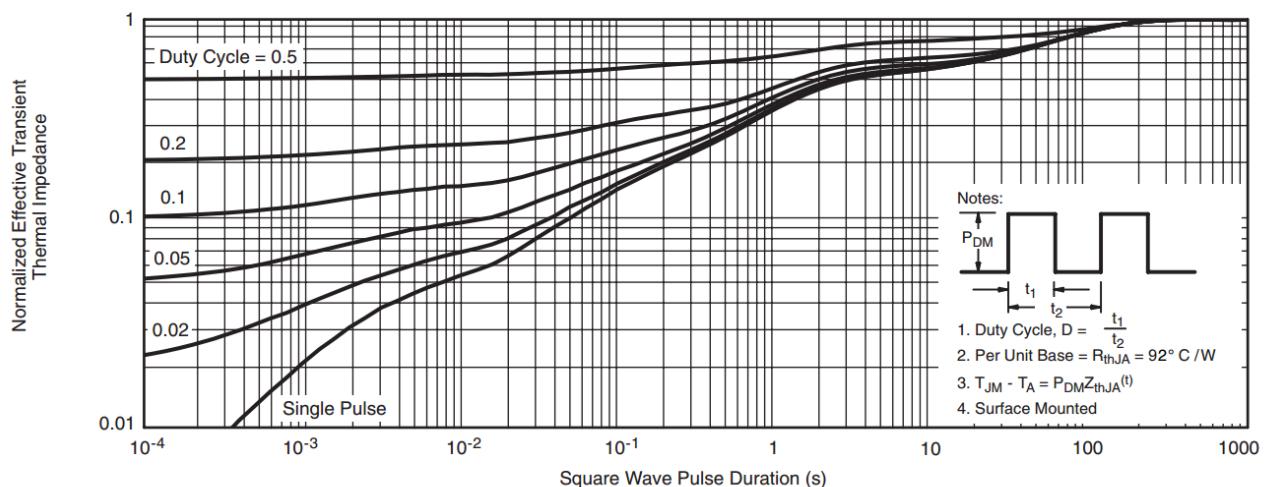
<b>THERMAL RESISTANCE RATINGS</b>					
Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient Thermal Resistance <sup>a</sup>	t ≤ 10 s	R <sub>θJA</sub>	90	108	°C/W
	Steady State		110	130	
Junction-to-Ambient Thermal Resistance <sup>b</sup>	t ≤ 10 s	R <sub>θJA</sub>	105	128	°C/W
	Steady State		133	158	
Junction-to-Case Thermal Resistance	Steady State	R <sub>θJC</sub>	60	75	

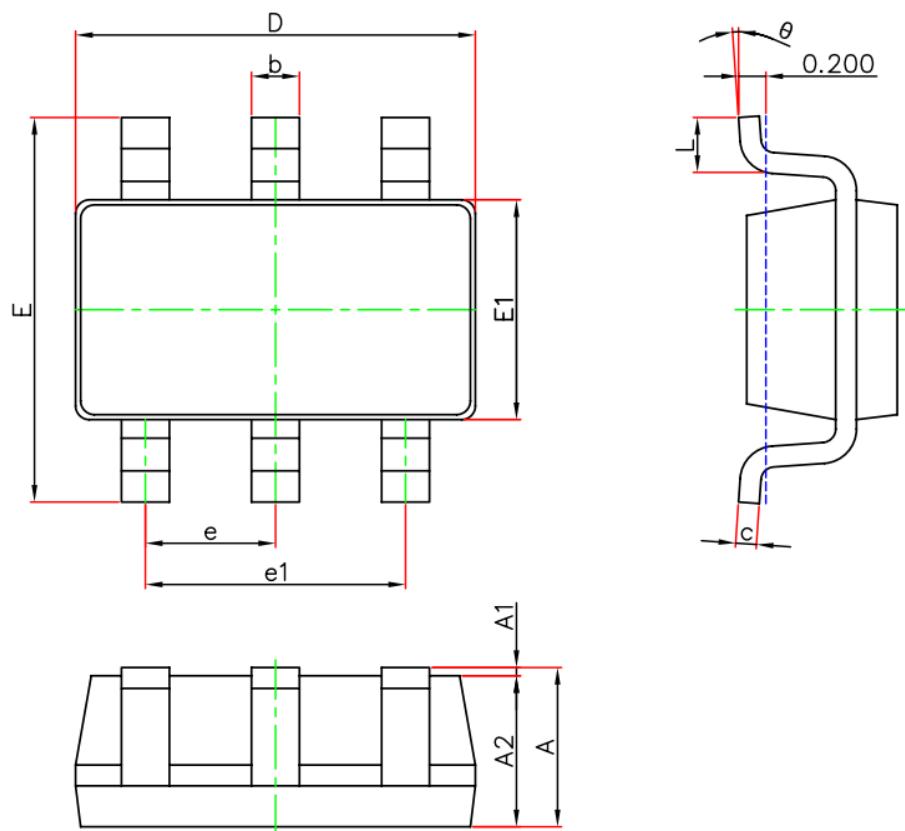
- a Surface mounted on FR4 Board using 1 square inch pad size, 1oz copper
- b Surface mounted on FR4 board using minimum pad size, 1oz copper
- c Maximum junction temperature T<sub>J</sub>=150° C.
- d Repetitive rating, pulse width limited by junction temperature, tp=10μs, Duty Cycle=1%.

**Electronics Characteristics (Ta=25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-to-Source Breakdown Voltage	BVDSS	V <sub>GS</sub> = 0 V, I <sub>D</sub> = -250μA	-20			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20 V, V <sub>GS</sub> = 0V			-1	uA
Gate-to-source Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ±12V			±100	nA
<b>ON CHARACTERISTICS</b>						
Gate Threshold Voltage	V <sub>GS(TH)</sub>	V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = -250μA	-0.3	-0.7	-1.5	V
Drain-to-source On-resistance <sup>e</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10V, ID = -5A		60	75	mΩ
		V <sub>GS</sub> = -4.5V, ID = -4A		70	95	
		V <sub>GS</sub> = -2.5V, ID = -2.5A		100	150	
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = -5 V, ID = -0.45A		5		S
<b>CHARGES, CAPACITANCES AND GATE RESISTANCE</b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>GS</sub> = 0 V, f = 1.0MHz, V <sub>DS</sub> = -15 V		471		pF
Output Capacitance	C <sub>OSS</sub>			51		
Reverse Transfer Capacitance	C <sub>RSS</sub>			46		
Total Gate Charge	Q <sub>G(TOT)</sub>	V <sub>GS</sub> = -10 V, V <sub>DS</sub> = -10 V, I <sub>D</sub> = -5A		7		nC
Gate-to-Source Charge	Q <sub>GS</sub>			0.6		
Gate-to-Drain Charge	Q <sub>GD</sub>			1.5		
<b>SWITCHING CHARACTERISTICS</b>						
Turn-On Delay Time	t <sub>d(ON)</sub>	V <sub>GS</sub> = -4.5V, V <sub>DS</sub> = -15V, ID=-4A, R <sub>G</sub> =5 Ω		12.8		ns
Rise Time	t <sub>r</sub>			12		
Turn-Off Delay Time	t <sub>d(OFF)</sub>			50.4		
Fall Time	t <sub>f</sub>			44.4		
<b>BODY DIODE CHARACTERISTICS</b>						
Forward Voltage	V <sub>SD</sub>	V <sub>GS</sub> = 0 V, I <sub>s</sub> = -0.9A		-0.84	-1.2	V

**Typical Characteristics (Ta=25°C, unless otherwise noted)**



**Total Gate Charge**

**Safe operating power**

**Transient thermal response (Junction-to-Ambient)**

**Package outline dimensions**
**SOT-23-6L**


Symbol	Dimensions In Millimeters	
	Min	Max
A	1.05	1.25
A1	0.00	0.10
A2	1.05	1.15
b	0.30	0.50
c	0.10	0.20
D	2.82	3.02
E	2.65	2.95
E1	1.50	1.70
e	0.95 (BSC)	
L	0.30	0.60
e1	1.80	2.00
θ	0 °	8 °